

A

B

C

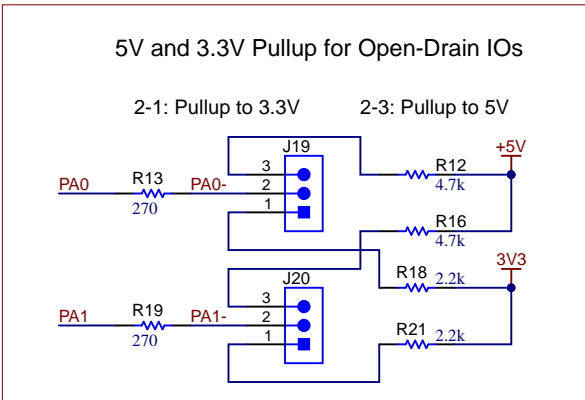
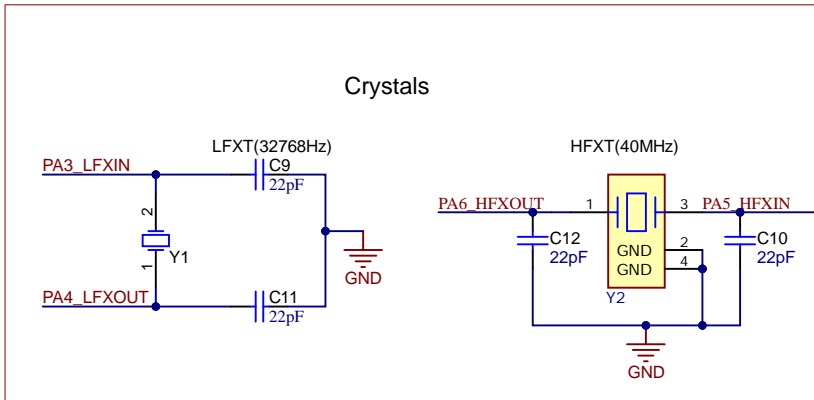
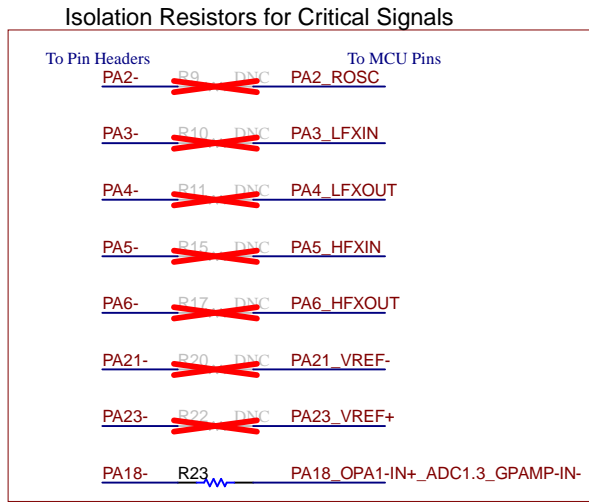
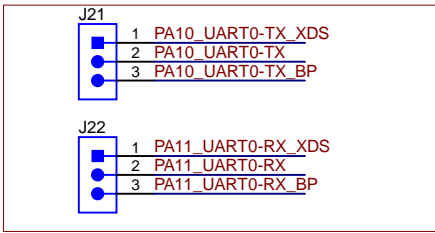
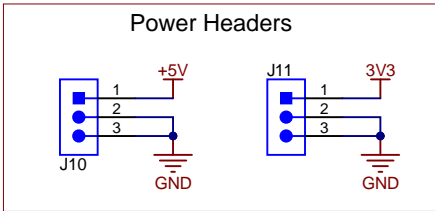
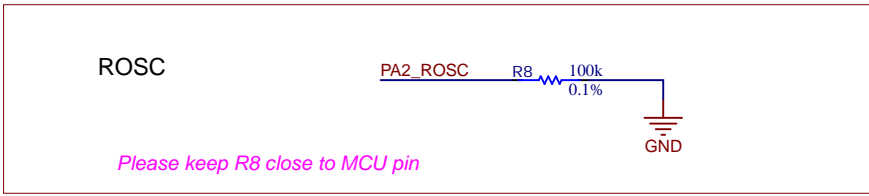
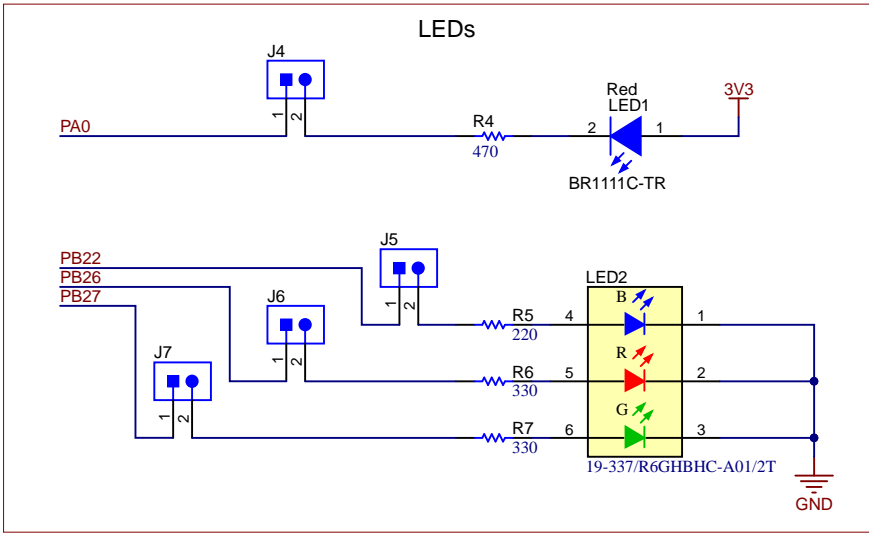
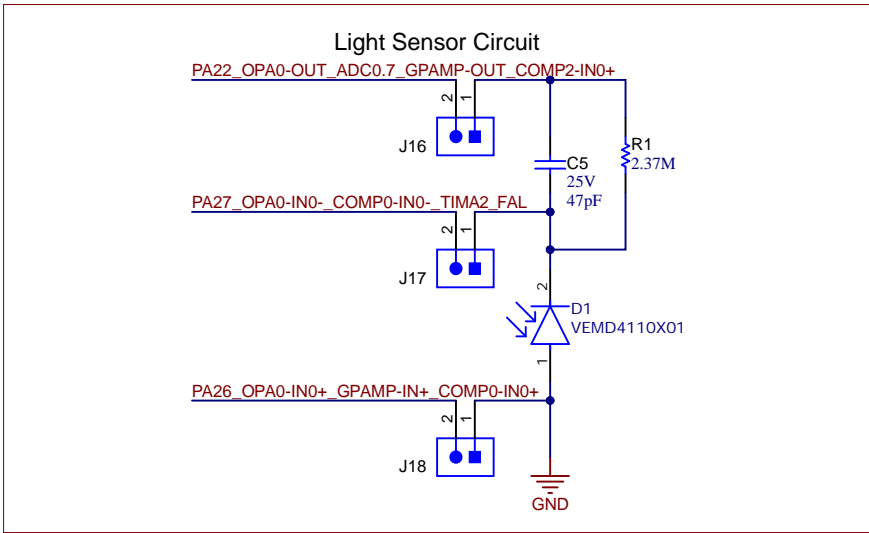
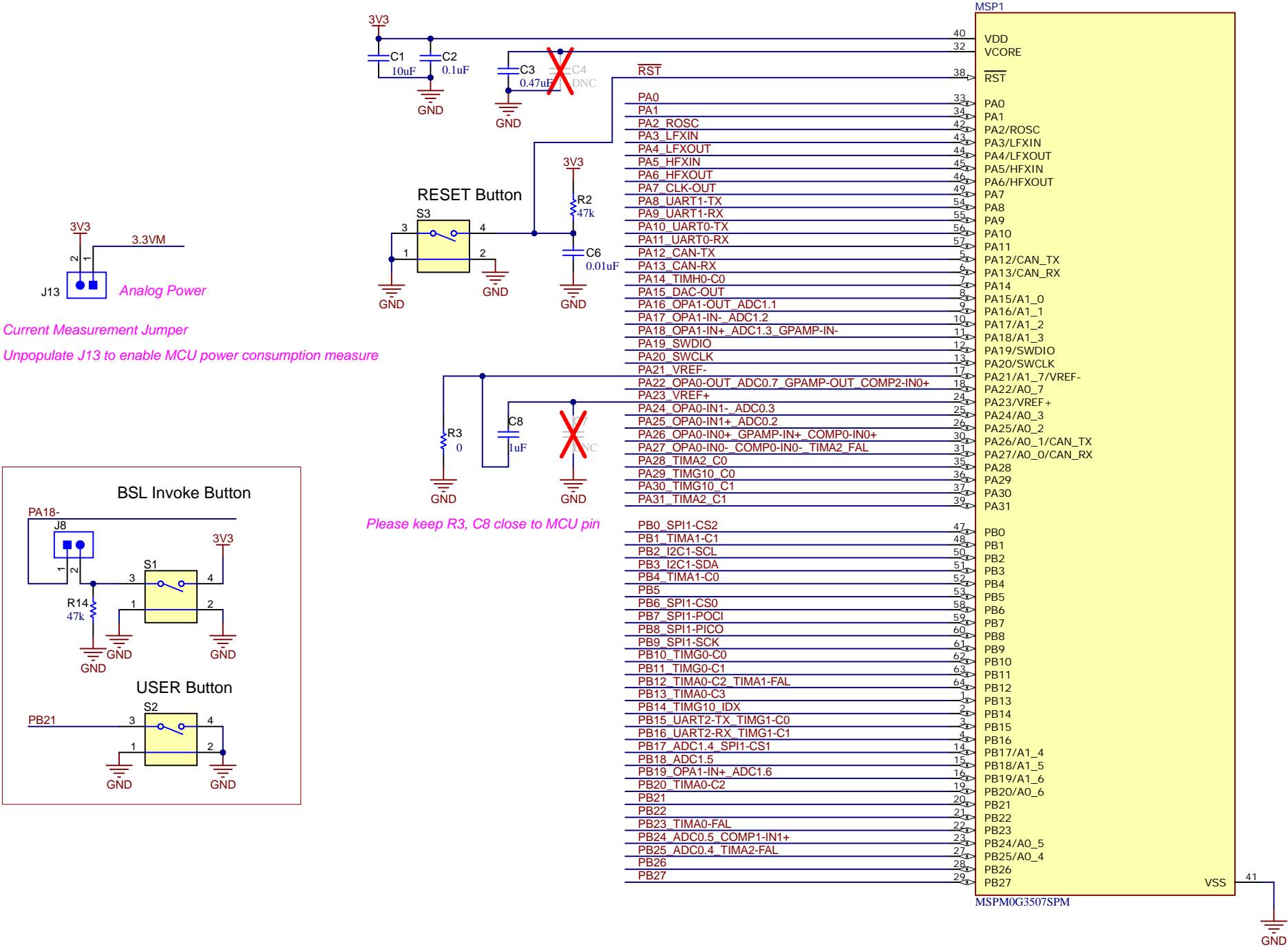
D

A

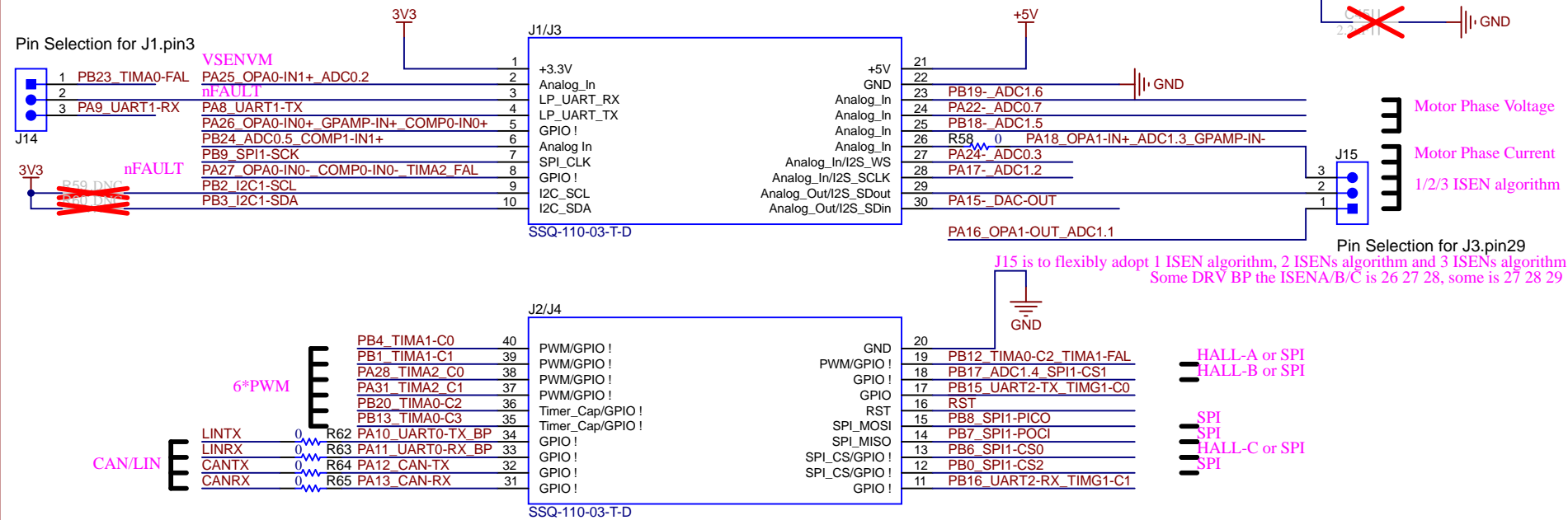
B

C

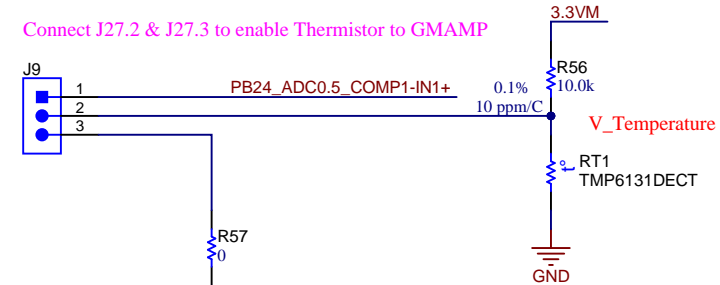
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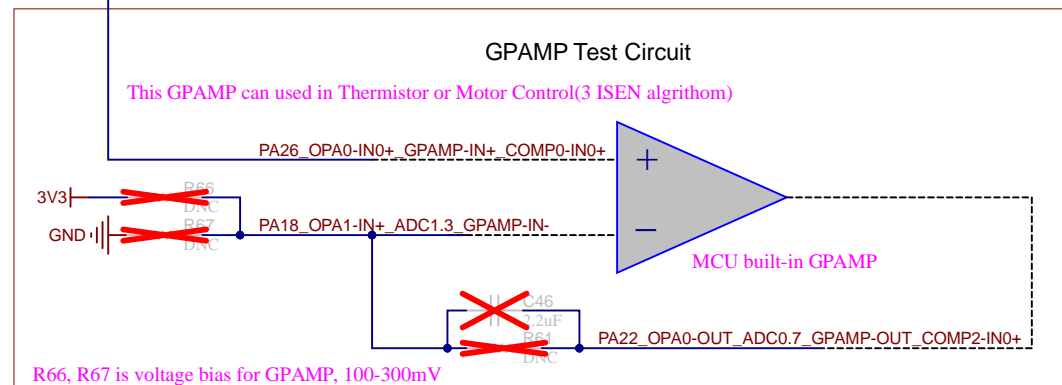
# BoosterPack Connectors



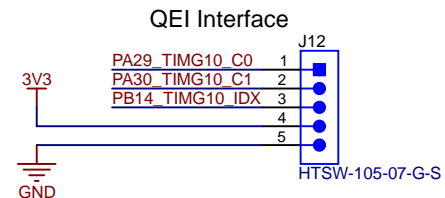
Connect J27.2 & J27.3 to enable Thermistor to GMAMP



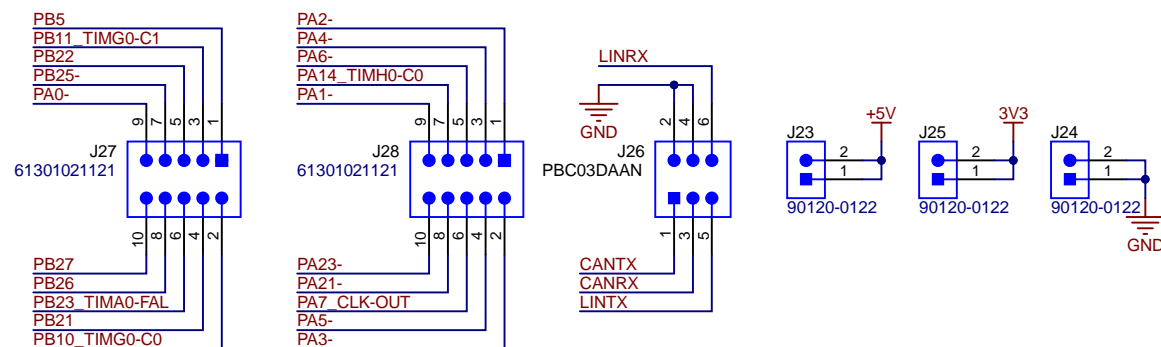
GPAMP can work in Buffer mode or Amplify mode via change R57, R61, R66, R67, C46



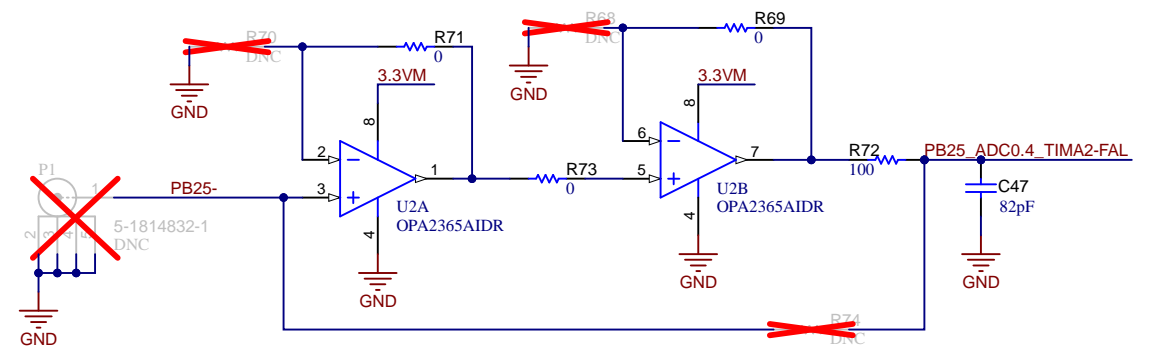
### Pin headers at the Low Side of the Board



PA19, PA20 are SWDIO, SWDCLK for debug/programming interface. They are on J101.pin14, pin16

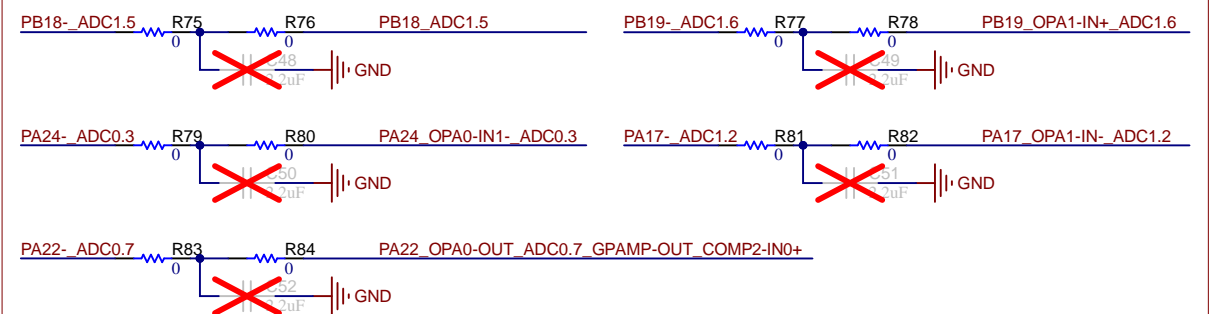


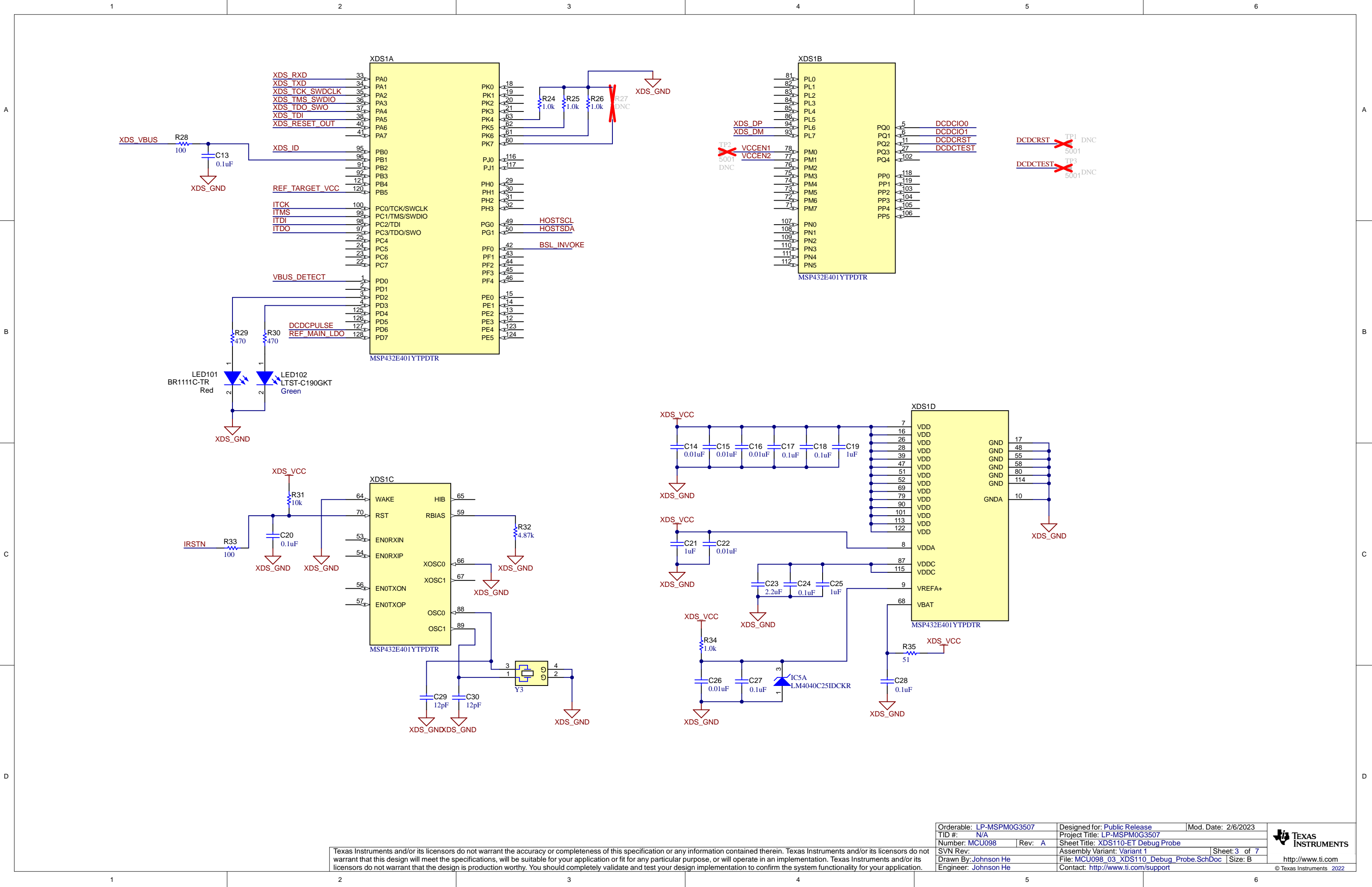
### ADC Input with Active Buffer



Default OPA2365 is populated for the ADC input test;  
If OPA2365 is NOT used, R72 need to be taked off and R74 0-ohm to be populated;

### RC Filter for ADC Input

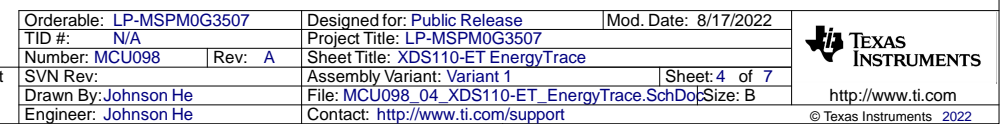




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Orderable: LP-MSPM0G3507	Designed for: Public Release	Mod. Date: 2/6/2023
TID #: N/A	Project Title: LP-MSPM0G3507	
Number: MCU098	Rev: A	Sheet Title: XDS110-ET Debug Probe
SVN Rev:	Assembly Variant: Variant 1	Sheet: 3 of 7
Drawn By: Johnson He	File: MCU098_03_XDS110_Debug_Probe.SchDoc	Size: B
Engineer: Johnson He	Contact: http://www.ti.com/support	

Energy measurement method protected under U.S. Patent Application 13/329,073 and subsequent patent applications



A

A

B

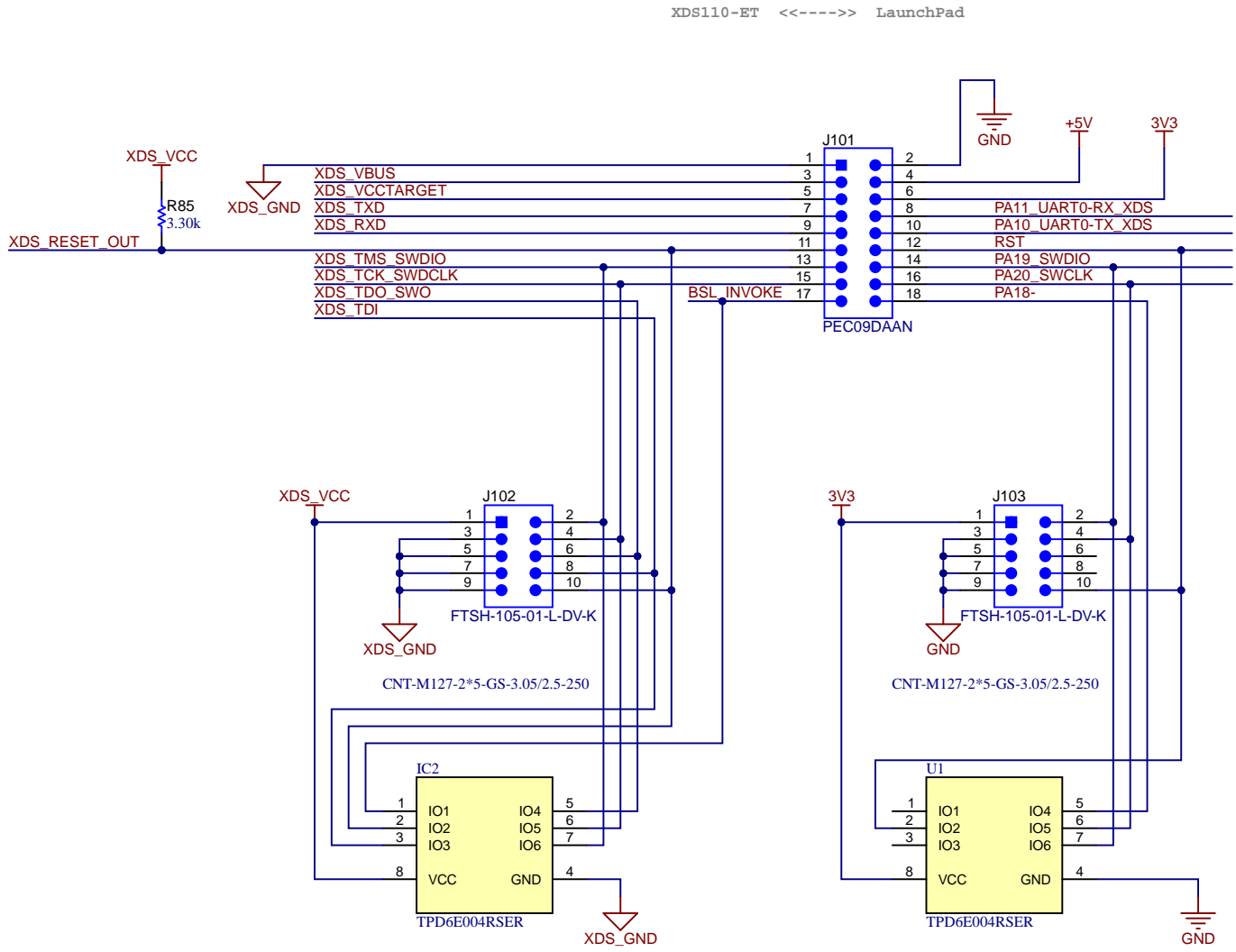
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C

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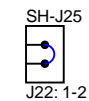
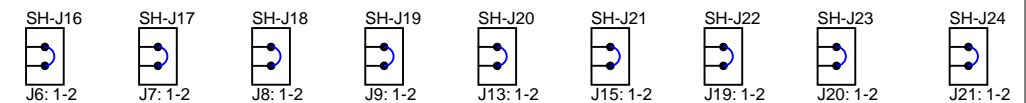
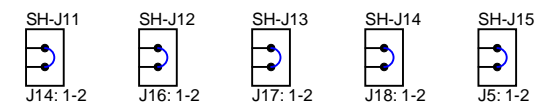
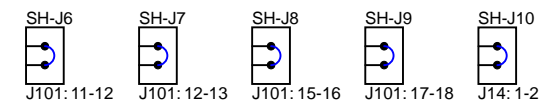
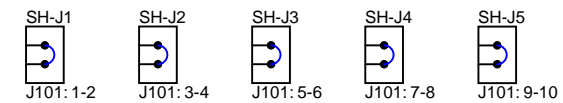
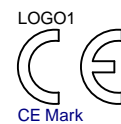
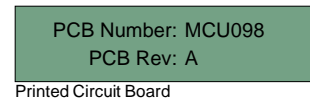
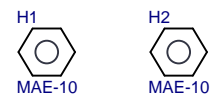
D



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A



USB1  
MECH  
AK67421-0.3

ZZ1

**Assembly Note**

These assemblies are ESD sensitive, ESD precautions shall be observed.

**ZZ2**

**Assembly Note**

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3


**Assembly Note**

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

**ZZ4**

**Assembly Note**

Place a click-in Standoff (MAE-10, KangYang) in hole MH1/MH2

Orderable: <a href="#">LP-MSPM0G3507</a>	Designed for: <a href="#">Public Release</a>	Mod. Date: 12/9/2022	 <b>TEXAS INSTRUMENTS</b>  <a href="http://www.ti.com">http://www.ti.com</a> © Texas Instruments 2022
TID #: <a href="#">N/A</a>	Project Title: <a href="#">LP-MSPM0G3507</a>		
Number: <a href="#">MCU098</a>	Rev: <a href="#">A</a>	Sheet Title: <a href="#">Hardware</a>	
SVN Rev:	Assembly Variant: <a href="#">Variant 1</a>	Sheet: <a href="#">7</a> of <a href="#">7</a>	
Drawn By: <a href="#">Johnson He</a>	File: <a href="#">MCU098_07_Hardware.SchDoc</a>	Size: B	
Engineer: <a href="#">Johnson He</a>	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		